

## EAST Search History

## EAST Search History (Prior Art)

Ref #	Hits	Search Query	DBs	Default Operator	Plurals	Time Stamp
L1	7830	(257/787-796).OCLS.	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	OFF	2010/09/01 21:18
L2	2838	(257/690).OCLS.	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	OFF	2010/09/01 21:18
L3	2967	(257/706-707).OCLS.	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	OFF	2010/09/01 21:18
L4	12995	1 2 3	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2010/09/01 21:18
L5	836	4 AND second near2 heat	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2010/09/01 21:19
L6	931	4 AND (second top bottom) near2 (thermal heat energy) near2 (sink spreader dissipation)	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2010/09/01 21:20
L7	9	4 AND (second top bottom) near2 (thermal heat energy) near2 (sink spreader dissipation) same metallization	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2010/09/01 21:21
L19	2	"5,143,865".pn.	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2010/09/01 21:27

L20	13	(( second top bottom) near2 (thermal heat energy) near2 (sink spreader dissipation) same metallization). ctm.	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2010/09/01 21:41
L21	18	("5027189"   "5156998"   "5198695" "5216278"   "5770468"   "5901901" "6134776"   "6284573"   "6391770").PN.	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2010/09/01 21:49
L22	40	die with integrated adj circuit adj region	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2010/09/01 21:49
L23	17	("3613001"   "3746973"   "3781681" "3803483"   "4479088"   "4486705" "4523144"   "4719417"   "4947114" "5059897").PN. OR ("5357192").URPN.	US-PGPUB; USPAT; USOCR	OR	ON	2010/09/01 21:49
L24	138	(dice chip die) with integrated adj circuit adj region	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2010/09/01 21:49
L25	138	L24 not L23	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2010/09/01 21:49
L26	98	L24 not L22	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2010/09/01 21:49
L27	111	wafer with integrated adj circuit adj region	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2010/09/01 21:49

L28	55	wafer with IC adj region	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2010/09/01 21:49
L29	1508	wafer with device adj region	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2010/09/01 21:49
L30	250	L29 and metallization	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2010/09/01 21:49
L31	17	("3613001"   "3746973"   "3781681"   "3803483"   "4479088"   "4486705"   "4523144"   "4719417"   "4947114"   "5059897").PN. OR ("5357192").URFN.	US-PGPUB; USPAT; USOCR	OR	ON	2010/09/01 21:49
L32	7	("5357192").URFN.	USPAT	OR	ON	2010/09/01 21:49
L33	32	("5414297"   "5559362"   "5665655"   "5698892").PN. OR ("5831330").URFN.	US-PGPUB; USPAT; USOCR	OR	ON	2010/09/01 21:49
L34	44	257/919	US-PGPUB; USPAT; USOCR	OR	ON	2010/09/01 21:49
L35	24	("5024970"   "5414297"   "5530280"   "5559362"   "5665655"   "5698892"   "5772906"   "5831330"   "5891808").PN. OR ("6300223").URFN.	US-PGPUB; USPAT; USOCR	OR	ON	2010/09/01 21:49
L36	31	("4228581"   "4356211"   "4922326"   "4976814"   "5017512"   "5024970"   "5096855"   "5136354"   "5157001").PN. OR ("5665655").URFN.	US-PGPUB; USPAT; USOCR	OR	ON	2010/09/01 21:49

L37	66457	wafer with metal coating with dicing	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2010/09/01 21:49
L38	540	wafer with metal with (layer film coating ) with dicing	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2010/09/01 21:49
L39	554	wafer with back with metallization	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2010/09/01 21:49
L40	20	wafer with back with metallization with thermal	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2010/09/01 21:49
L41	27	wafer with back with metallization with dicing	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2010/09/01 21:49
L42	2	"6,853,070".pn.	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2010/09/01 21:49
L43	2	"6,717,267".pn.	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2010/09/01 21:49
L44	1774	(257/704).CCLS.	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	OFF	2010/09/01 21:49

L45	186	L44 and heat with lid	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2010/09/01 21:49
L46	211	L44 and heat near3 (sink spreader slung) and wire	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2010/09/01 21:49
L47	11	("20010008776"   "20020175421"   "20020195270"   "5424573"   "5616957"   "5977626"   "6414385"   "6437984"   "6608763"   "6703698"   "6734552").PN.	US-PGPUB; USPAT; USOCR	OR	ON	2010/09/01 21:49
L48	106	("5705851"   "5904497"   "6002181"   "6072239"   "6177721"   "6184580"   "6198171").PN. OR ("6414385").URPN.	US-PGPUB; USPAT; USOCR	OR	ON	2010/09/01 21:49
L49	20	("20010008776"   "20020175421"   "20020195270"   "5424573"   "5616957"   "5977626"   "6414385"   "6437984"   "6608763"   "6703698"   "6734552").PN. OR ("6849940").URPN.	US-PGPUB; USPAT; USOCR	OR	ON	2010/09/01 21:49
L50	82	("5397917"   "5583378"   "5724230"   "5726493"   "5796038"   "5854511"   "5866943"   "5886408"   "5909056"   "5926371"   "6020637"   "6046499").PN. OR ("6184580").URPN.	US-PGPUB; USPAT; USOCR	OR	ON	2010/09/01 21:49
L51	1	"6,853,070".pn.	US-PGPUB; USPAT; USOCR	OR	ON	2010/09/01 21:49

L52	28	("5027189"   "5156998"   "5198695" "5216278"   "5665655"   "5770468" "5901901"   "5977626"   "6134776" "6284573"   "6391770"   "6717267" "6812548"   "6853070").PN.	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2010/09/01 21:49
L53	82	("5397917"   "5583378"   "5724230" "5726493"   "5796038"   "5854511" "5866943"   "5886408"   "5909056" "5926371"   "6020637"   "6046499").PN. OR ("6184580").URPN.	US-PGPUB; USPAT; USOCR	OR	ON	2010/09/01 21:49
L54	144	active with surface with thermal with vias	US-PGPUB; USPAT; USOCR	OR	ON	2010/09/01 21:49
L55	974	die with thermal with vias	US-PGPUB; USPAT; USOCR	OR	ON	2010/09/01 21:49
L56	476	die with thermal with vias	USPAT; USOCR	OR	ON	2010/09/01 21:49
L57	10	("5068714"   "5074947"   "5386624" "5492863"   "5616206"   "5820716" "5842273"   "5843251"   "6000127" "6042682").PN.	US-PGPUB; USPAT; USOCR	OR	ON	2010/09/01 21:49
L58	2	("5216278"   "5287001").PN.	US-PGPUB; USPAT; USOCR	OR	ON	2010/09/01 21:49
L59	35	("3896544"   "4479140"   "4827376" "4829403").PN. OR ("5287001").URPN.	US-PGPUB; USPAT; USOCR	OR	ON	2010/09/01 21:49
L60	4	netflix	US-PGPUB; USPAT; USOCR	OR	ON	2010/09/01 21:49
L61	334	netflix	US-PGPUB; USPAT; USOCR	OR	ON	2010/09/01 21:49
L62	1	"6584450".pn.	US-PGPUB; USPAT; USOCR	OR	ON	2010/09/01 21:49

L63	12	("5397917"   "5583378"   "5724230" "5726493"   "5796038"   "5854511" "5866943"   "5886408"   "5909056" "5926371"   "6020637"   "6046499").PN.	US-PGPUB; USPAT; USOCR	OR	ON	2010/09/01 21:49
L64	82	("5397917"   "5583378"   "5724230" "5726493"   "5796038"   "5854511" "5866943"   "5886408"   "5909056" "5926371"   "6020637"   "6046499").PN. OR ("6184580").URPN.	US-PGPUB; USPAT; USOCR	OR	ON	2010/09/01 21:49
L65	552	(257/796).CCLS.	USPAT; USOCR	OR	OFF	2010/09/01 21:49
L66	23	("20030137061"   "20050139997"   "5252855"   "5328811" "5365107"   "5397921"   "5409865" "5493153"   "5578869"   "5844168" "5851337"   "5877552"   "5905634" "5933324"   "5977626"   "6020637" "6146921"   "6201302"   "6246115" "6323065"   "6400014"   "6451448" "6509642").PN.	US-PGPUB; USPAT; USOCR	OR	ON	2010/09/01 21:49
L67	5	("5216283"   "5444909"   "5705851" "5719442"   "5773886").PN.	US-PGPUB; USPAT; USOCR	OR	ON	2010/09/01 21:49
L68	4	("5108955"   "5609315"   "6146921" "6206997").PN.	US-PGPUB; USPAT; USOCR	OR	ON	2010/09/01 21:49
L69	66	("4266239"   "4541005"   "4778641" "4822550"   "4823234"   "4868638" "4890152").PN. OR ("5108955").URPN.	US-PGPUB; USPAT; USOCR	OR	ON	2010/09/01 21:49
L70	988	die with pad with passivation	US-PGPUB; USPAT; USOCR	OR	ON	2010/09/01 21:49

L71	0	chip with pad with passivation with encapsulation\$3	USPAT	OR	ON	2010/09/01 21:49
L72	105	chip with pad with passivation	JPO	OR	ON	2010/09/01 21:49
L73	9	chip with back with surface with passivation	JPO	OR	ON	2010/09/01 21:49
L74	0	(die chip wafer) with dicing with passivation	JPO	OR	ON	2010/09/01 21:49
L75	41	(die chip wafer) with dicing with passivation	JPO	OR	ON	2010/09/01 21:49
L76	685	pad with molding with surface same (IC die chip wafer)	USPAT	OR	ON	2010/09/01 21:49
L77	9	("20010015489"   "20020197771"   "20040253764"   "5976912"   "6534330"   "6562660"   "6969905").PN. OR ("7064011").URPN.	US-PGPUB; USPAT; USOCR	OR	ON	2010/09/01 21:49
L78	5	("5070041"   "6331453").PN. OR ("6673656").URPN.	US-PGPUB; USPAT; USOCR	OR	ON	2010/09/01 21:49
L79	55	LED with silicon with sink and led with diode	US-PGPUB; USPAT; USOCR	OR	ON	2010/09/01 21:49
L80	14	LED with silicone with sink and led with diode	US-PGPUB; USPAT; USOCR	OR	ON	2010/09/01 21:49
L81	8	("5175610"   "5319241"   "5467253"   "5496775"   "5686362").PN. OR ("6569755").URPN.	US-PGPUB; USPAT; USOCR	OR	ON	2010/09/01 21:49
L82	78	("3212160"   "4600600"   "4807021"   "4899107"   "5071787"   "5143865"   "5289346"   "5341564"   "5348607").PN. OR ("5496775").URPN.	US-PGPUB; USPAT; USOCR	OR	ON	2010/09/01 21:49
L83	42	("4558510"   "4818724").PN. OR ("5143865").URPN.	US-PGPUB; USPAT; USOCR	OR	ON	2010/09/01 21:49



L84	2	"6,717,267".pn.	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2010/09/01 21:49
L85	2	"5,977,626".pn.	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2010/09/01 21:49
L86	27	"5,665,655"	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2010/09/01 21:49
L87	2	"5,665,655".pn.	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2010/09/01 21:49
L88	2	"5143865".pn.	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2010/09/01 21:49
L89	2	"6,717,267".pn.	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2010/09/01 21:49
S1	18	("5027189"   "5156998"   "5198695"   "5216278"   "5770468"   "5901901"   "6134776"   "6284573"   "6391770").PN.	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2005/08/09 13:12
S2	5	die with integrated adj circuit adj region	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2005/08/09 13:15

S3	12	("3613001"   "3746973"   "3781681"   "3803483"   "4479088"   "4486705"   "4523144"   "4719417"   "4947114"   "5059897").PN. OR ("5357192").URPN.	US-PGPUB; USPAT; USOCR	OR	ON	2005/08/09 13:15
S4	45	(dice chip die) with integrated adj circuit adj region	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2005/08/09 13:41
S5	45	S4 not S3	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2005/08/09 13:16
S6	40	S4 not S2	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2005/08/09 13:16
S7	59	wafer with integrated adj circuit adj region	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2005/08/09 13:42
S8	25	wafer with IC adj region	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2005/08/09 13:43
S9	857	wafer with device adj region	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2005/08/09 13:43
S10	175	S9 and metallization	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2005/08/09 13:44

S11	12	("3613001"   "3746973"   "3781681"   "3803483"   "4479088"   "4486705"   "4523144"   "4719417"   "4947114"   "5059897").PN. OR ("5357192").URPN.	US-PGPUB; USPAT; USOCR	OR	ON	2005/08/09 13:47
S12	2	("5357192").URPN.	USPAT	OR	ON	2005/08/09 13:47
S13	20	("5414297"   "5559362"   "5665655"   "5698892").PN. OR ("5831330").URPN.	US-PGPUB; USPAT; USOCR	OR	ON	2005/08/09 14:05
S14	31	257/919	US-PGPUB; USPAT; USOCR	OR	ON	2005/08/09 14:06
S15	14	("5024970"   "5414297"   "5530280"   "5559362"   "5665655"   "5698892"   "5772906"   "5831330"   "5891808").PN. OR ("6300223").URPN.	US-PGPUB; USPAT; USOCR	OR	ON	2005/08/09 14:29
S16	21	("4228581"   "4356211"   "4922326"   "4976814"   "5017512"   "5024970"   "5096855"   "5136354"   "5157001").PN. OR ("5665655").URPN.	US-PGPUB; USPAT; USOCR	OR	ON	2005/08/09 16:20
S36	38794	wafer with metal coating with dicing	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2005/08/10 07:47
S37	237	wafer with metal with (layer film coating ) with dicing	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2005/08/10 07:49
S38	243	wafer with back with metallization	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2005/08/10 07:49

S39	8	wafer with back with metallization with thermal	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2005/08/10 07:58
S40	13	wafer with back with metallization with dicing	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2005/08/10 10:14
S41	2	"6,853,070".pn.	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2005/08/10 10:15
S42	2	"6,717,267".pn.	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2005/08/10 10:38
S43	1261	(257/704).CCLS.	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	OFF	2005/08/10 10:41
S44	103	S43 and heat with lid	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2005/08/10 10:43
S45	142	S43 and heat near3 (sink spreader slung) and wire	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2005/08/10 10:43
S46	11	("20010008776"   "20020175421"   "20020195270"   "5424573"   "5616957"   "5977626"   "6414385"   "6437984"   "6608763"   "6703698"   "6734552").PN.	US-PGPUB; USPAT; USOCR	OR	ON	2005/08/10 10:44

S47	31	("5705851"   "5904497"   "6002181"   "6072239"   "6177721"   "6184580" "6198171").PN. OR ("6414385").URFN.	US-PGPUB; USPAT; USOCR	OR	ON	2005/08/10 10:45
S48	11	("20010008776"   "20020175421"   "20020195270"   "5424573"   "5616957"   "5977626"   "6414385"   "6437984"   "6608763"   "6703698"   "6734552").PN. OR ("6849940").URFN.	US-PGPUB; USPAT; USOCR	OR	ON	2005/08/10 10:46
S49	40	("5397917"   "5583378"   "5724230"   "5726493"   "5796038"   "5854511"   "5866943"   "5886408"   "5909056"   "5926371"   "6020637"   "6046499").PN. OR ("6184580").URFN.	US-PGPUB; USPAT; USOCR	OR	ON	2005/08/10 11:22
S50	1	"6,853,070".pn.	US-PGPUB; USPAT; USOCR	OR	ON	2005/08/10 11:23
S51	28	("5027189"   "5156998"   "5198695"   "5216278"   "5665655"   "5770468"   "5901901"   "5977626"   "6134776"   "6284573"   "6391770"   "6717267"   "6812548"   "6853070").PN.	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2006/01/21 21:32
S52	46	("5397917"   "5583378"   "5724230"   "5726493"   "5796038"   "5854511"   "5866943"   "5886408"   "5909056"   "5926371"   "6020637"   "6046499").PN. OR ("6184580").URFN.	US-PGPUB; USPAT; USOCR	OR	ON	2006/04/05 15:02
S53	69	active with surface with thermal with vias	US-PGPUB; USPAT; USOCR	OR	ON	2006/04/05 15:03
S54	515	die with thermal with vias	US-PGPUB; USPAT; USOCR	OR	ON	2006/04/05 15:04

S55	299	die with thermal with vias	USPAT; USOCR	OR	ON	2006/04/05 15:04
S56	10	("5068714"   "5074947"   "5386624" "5492863"   "5616206"   "5820716" "5842273"   "5843251"   "6000127" "6042682").PN.	US-PGPUB; USPAT; USOCR	OR	ON	2006/04/05 15:11
S57	2	("5216278"   "5287001").PN.	US-PGPUB; USPAT; USOCR	OR	ON	2006/04/05 15:14
S58	24	("3896544"   "4479140"   "4827376" "4829403").PN. OR ("5287001").URPN.	US-PGPUB; USPAT; USOCR	OR	ON	2006/04/05 15:52
S59	0	netflix	US-PGPUB; USPAT; USOCR	OR	ON	2006/04/05 15:53
S60	43	netflix	US-PGPUB; USPAT; USOCR	OR	ON	2006/04/05 16:06
S61	1	"6584450".pn.	US-PGPUB; USPAT; USOCR	OR	ON	2006/04/05 16:07
S62	12	("5397917"   "5583378"   "5724230" "5726493"   "5796038"   "5854511" "5866943"   "5886408"   "5909056" "5926371"   "6020637"   "6046499").PN.	US-PGPUB; USPAT; USOCR	OR	ON	2006/04/06 14:15
S63	46	("5397917"   "5583378"   "5724230" "5726493"   "5796038"   "5854511" "5866943"   "5886408"   "5909056" "5926371"   "6020637"   "6046499").PN. OR ("6184580").URPN.	US-PGPUB; USPAT; USOCR	OR	ON	2006/04/06 14:21
S64	469	(257/796).CCLS.	USPAT; USOCR	OR	OFF	2006/12/06 16:00

S65	23	("20030137061"   "20050139997"   "5252855"   "5328811" "5365107"   "5397921"   "5409865" "5493153"   "5578869"   "5844168" "5851337"   "5877552"   "5905634" "5933324"   "5977626"   "6020637" "6146921"   "6201302"   "6246115" "6323065"   "6400014"   "6451448" "6509642").PN.	US-PGPUB; USPAT; USOCR	OR	ON	2006/12/06 16:02
S66	5	("5216283"   "5444909"   "5705851" "5719442"   "5773886").PN.	US-PGPUB; USPAT; USOCR	OR	ON	2006/12/06 16:03
S67	4	("5108955"   "5609315"   "6146921" "6206997").PN.	US-PGPUB; USPAT; USOCR	OR	ON	2006/12/06 16:04
S68	60	("4266239"   "4541005"   "4778641" "4822550"   "4823234"   "4868638" "4890152").PN. OR ("5108955").URPN.	US-PGPUB; USPAT; USOCR	OR	ON	2006/12/06 16:19
S69	627	die with pad with passivation	US-PGPUB; USPAT; USOCR	OR	ON	2006/12/06 16:19
S70	0	chip with pad with passivation with encapsalt\$3	USPAT	OR	ON	2006/12/06 16:20
S71	91	chip with pad with passivation	JPO	OR	ON	2006/12/06 16:20
S72	7	chip with back with surface with passivation	JPO	OR	ON	2006/12/06 16:22
S73	0	(die chip wafer) with dicing with passivation	JPO	OR	ON	2006/12/06 16:23
S74	31	(die chip wafer) with dicing with passivation	JPO	OR	ON	2006/12/06 16:24
S75	506	pad with molding with surface same (IC die chip wafer)	USPAT	OR	ON	2006/12/06 16:24

S76	7	("20010015489"   "20020197771"   "20040253764"   "5976912"   "6534330"   "6562660"   "6969905").PN. OR ("7064011").URPN.	US-PGPUB; USPAT; USOCR	OR	ON	2006/12/06 16:25
S77	3	("5070041"   "6331453").PN. OR ("6673656").URPN.	US-PGPUB; USPAT; USOCR	OR	ON	2006/12/06 16:50
S78	23	LED with silicon with sink and led with diode	US-PGPUB; USPAT; USOCR	OR	ON	2006/12/06 16:51
S79	7	LED with silicone with sink and led with diode	US-PGPUB; USPAT; USOCR	OR	ON	2006/12/06 16:51
S80	6	("5175610"   "5319241"   "5467253"   "5496775"   "5686362").PN. OR ("6569755").URPN.	US-PGPUB; USPAT; USOCR	OR	ON	2006/12/06 17:13
S81	53	("3212160"   "4600600"   "4807021"   "4899107"   "5071787"   "5143865"   "5289346"   "5341564"   "5348607").PN. OR ("5496775").URPN.	US-PGPUB; USPAT; USOCR	OR	ON	2006/12/06 17:14
S82	37	("4558510"   "4818724").PN. OR ("5143865").URPN.	US-PGPUB; USPAT; USOCR	OR	ON	2006/12/06 17:20
S83	2	"6,717,267".pn.	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2006/12/06 17:53
S84	2	"5,977,626".pn.	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2006/12/06 18:22
S85	16	"5,665,655"	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2006/12/06 18:23



S86	2	"5,665,655".pn.	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2006/12/06 18:36
S87	2	"5143865".pn.	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2006/12/06 18:36
S88	2	"6,717,267".pn.	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2006/12/07 10:06

9/ 1/ 2010 10:57:26 PM

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